ENVIRO Clean Them!

The production proven resist and residue removal tool

Shift your resist and removal process into high gear with the production proven ULVAC Enviro™. Enviro's versatile dual plasma source technology integrates downstream microwave ashing and non-damaging RIE (Reactive Ion Etching) to tackle the tough jobs like:

- BEOL layers — eliminates the need for post-strip solvent clean – saves time and money
- High dose implant layers — the dual plasma source gives the highest throughput in the industry and virtually eliminates the need for solvents

For the tough jobs like yours, the clean and fast, production proven solution is Enviro. Save time, save money and keep the environment clean too!

ULVAC Technologies, Inc
401 Griffin Brook Drive
Methuen, MA 01844
Phone: 978-686-7550
Fax: 978-689-6300
www.ulvac.com

ULVAC

Integrated

copper metrology that's affordable.

MESEC –

the cost effective, in-tool copper film thickness and uniformity measurement system.

Using enhanced Eddy current detection technology, MESEC provides reliable, integrated copper film measurements so you can make fast corrections to your 300mm copper process. And you can buy MESEC at a fraction of the cost of competitive systems. MESEC can be integrated with all leading electroplating tools and features:

- Non-contact, non-destructive measurements
- Direct evaluation of device wafers, not test wafers
- The same uncompromising performance with integrated or stand-alone models

So, whether you're retrofitting your existing process tool, integrating it into your new tool or using it as a stand-alone – with MESEC you're going to save some copper in the process.

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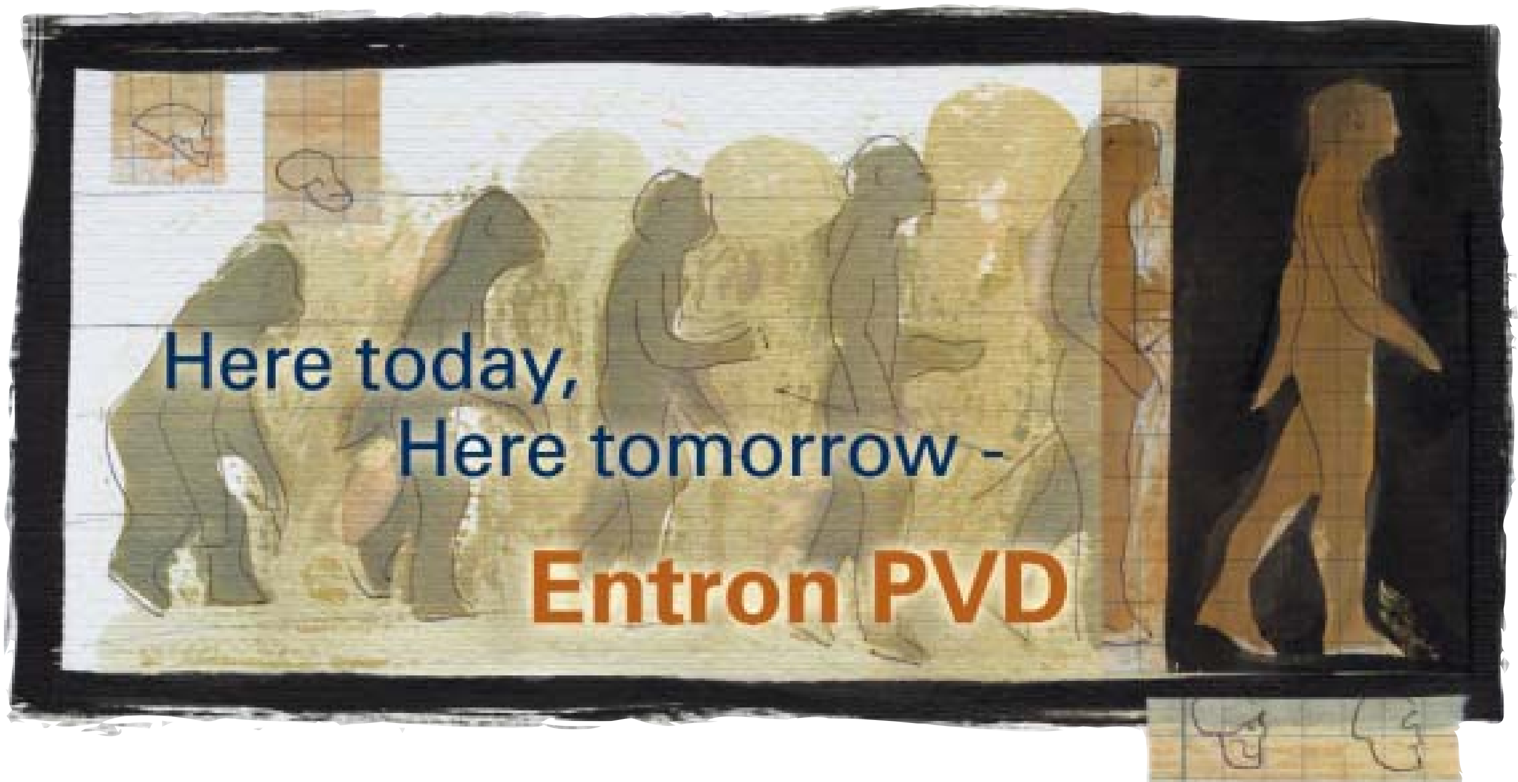
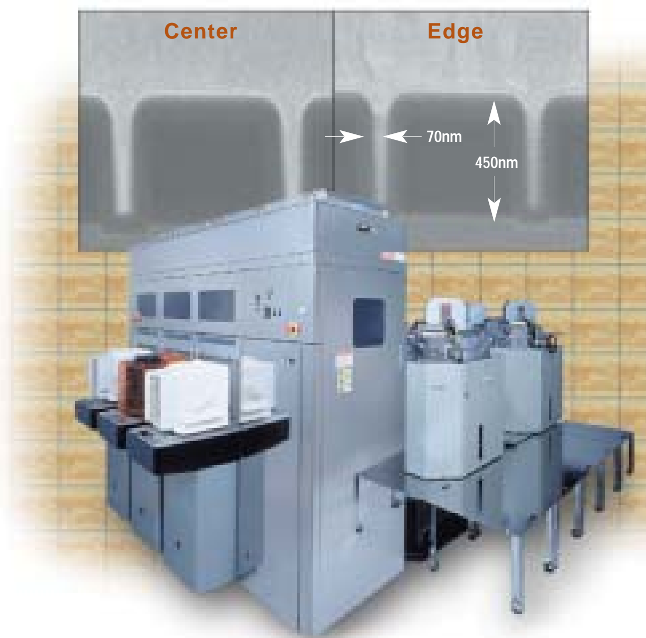


The only PVD tool that takes you to the 45nm generation

Ulvac's Entron is the world's most advanced metallization system available today for tomorrow's process requirements. Whether you're using PVD or ALD/PVD, Entron brings you to the 45nm node.

With a proven track record throughout Asia, Entron uses Bias Modulated Self-Ionized Sputter (SIS)* technology to improve the bottom and sidewall coverage of barrier metal and Cu seed films. This uniform coverage results in excellent electroplating filling performance and higher interconnect reliability.



Entron features:

- Proven process utilizing PVD technology
- Simple planar targets
- Small footprint
- Easy tool maintenance
- Lower cost and lowest cost of ownership

So whether you're using PVD or ALD/PVD, Entron technology is here for you today and all the way down to 45nm.

For more information about Entron, call 978-686-7550 or email us at: entron@ulvac.com.

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*Contact ULVAC for technical papers on SIS extendibility to the 45nm node.